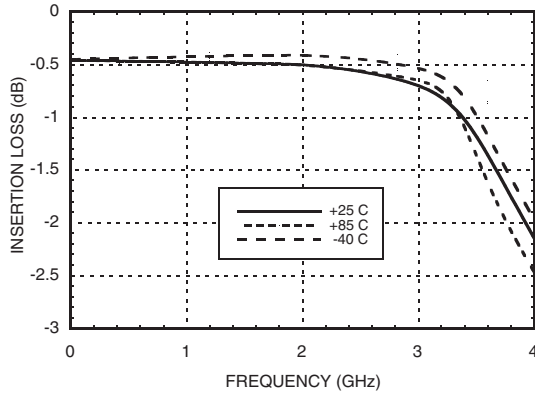
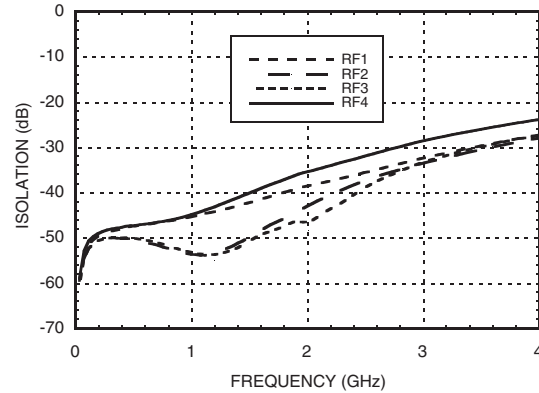




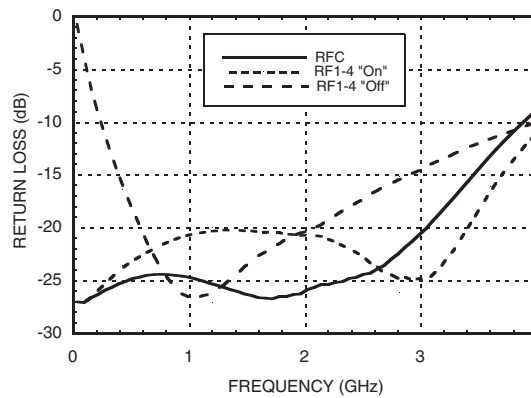
Insertion Loss



Isolation



Return Loss



Bias Voltage & Current

Vdd Range = +5.0 Vdc ± 10%		
Vdd (Vdc)	Idd (Typ.) (mA)	Idd (Max.) (mA)
+5.0	4.0	7.0

Truth Table

Control Input		Signal Path State
A	B	RFCOM to:
LOW	LOW	RF1
HIGH	LOW	RF2
LOW	HIGH	RF3
HIGH	HIGH	RF4

TTL/CMOS Control Voltages

State	Bias Condition
Low	0 to +0.8 Vdc @ 5uA Typ.
High	+2.0 to +5.0 Vdc @ 70 uA Typ.

NOTE:

DC Blocking capacitors are required at ports RFC and RF1, 2, 3, 4.

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Absolute Maximum Ratings

Bias Voltage Range (Port Vdd)	+7.0 Vdc
Control Voltage Range (A & B)	-0.5V to Vdd +1 Vdc
Channel Temperature	150 °C
Thermal Resistance (Insertion Loss Path)	210 °C/W
Thermal Resistance (Terminated Path)	250 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
Maximum Input Power Vdd = +5 Vdc	+20 dBm (0.05 - 0.5 GHz) +27 dBm (0.5 - 3.5 GHz)

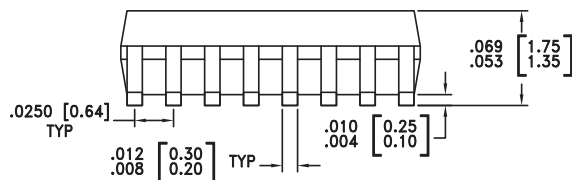
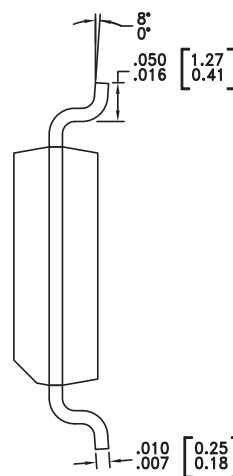
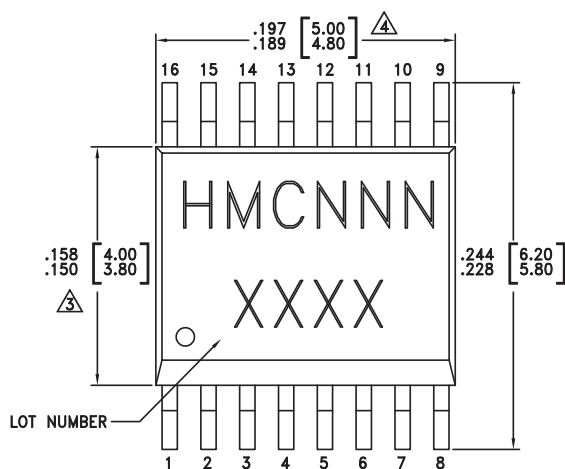


ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

10

SWITCHES - SMT

Outline Drawing



NOTES:

- LEADFRAME MATERIAL: COPPER ALLOY
- DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Leadframe Plating	MSL Rating	Package Marking ^[3]
HMC241QS16	Low Stress Injection Molding Plastic Silica and Silicon Impregnated	Sn/Pb Solder	MSL1 ^[1]	HMC241 XXXX
HMC241QS16E	RoHS-compliant Low Stress Injection Molding Plastic Silica and Silicon Impregnated	100% Matte Tin	MSL1 ^[2]	HMC241 XXXX

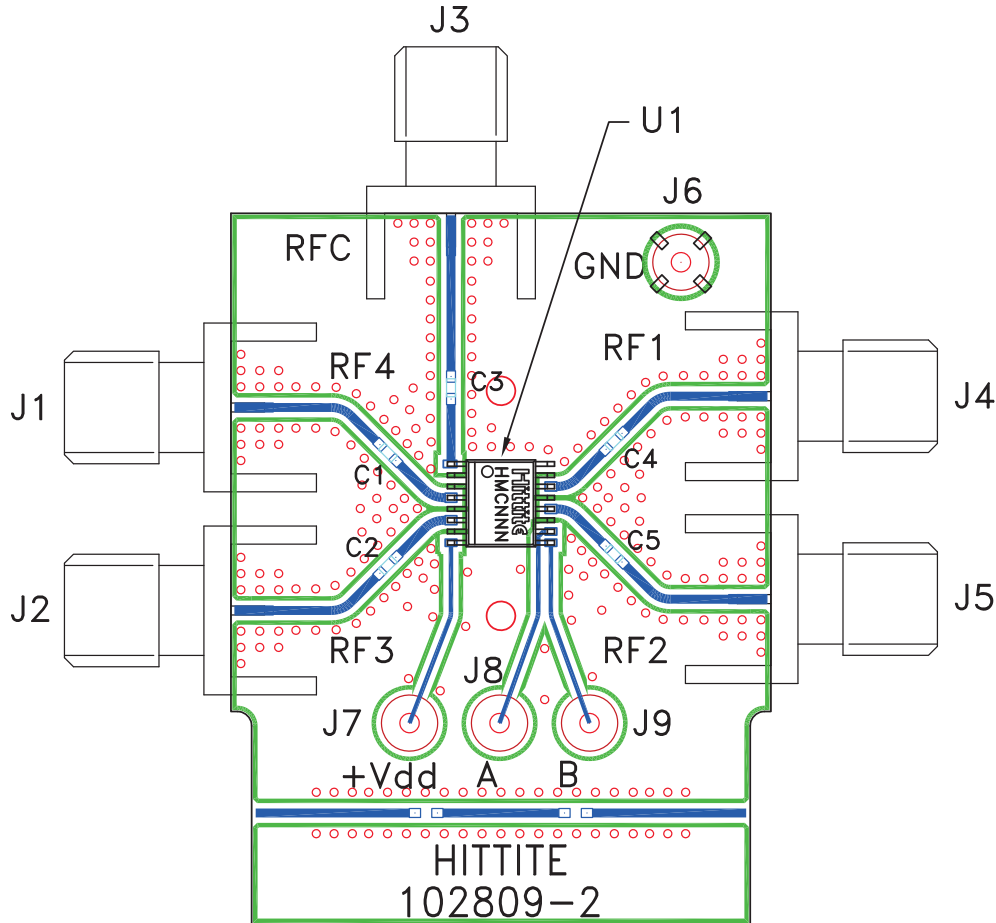
[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX



Evaluation PCB



List of Materials for Evaluation PCB 102913 ^[1]

Item	Description
J1 - J5	PCB Mount SMA RF Connector
J6 - J9	DC Pin
C1 - C5	330 pF capacitor, 0402 Pkg.
U1	HMC241QS16 / HMC241QS16E SP4T Switch
PCB ^[2]	102809 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.